

Specification of Thermoelectric Module

TEC3-127-71-31-03

Description

The TEC3-127-71-31-03 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 127-71-31 couples module in size of 20mm×20mm (top)/40mm ×40mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

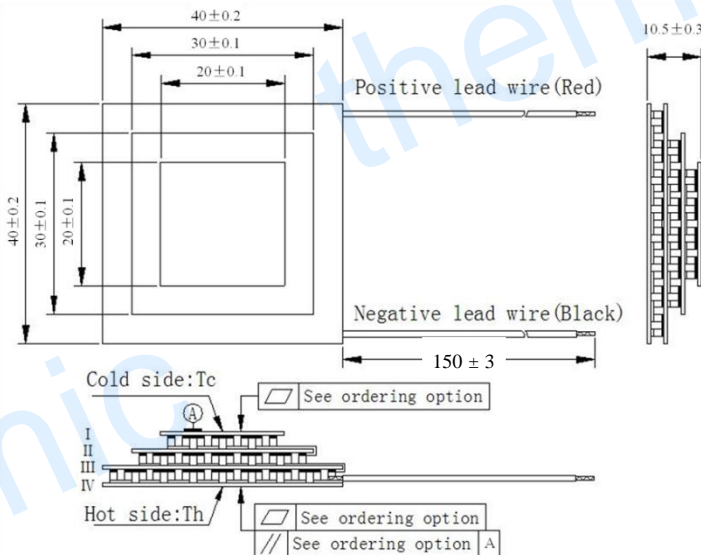
Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	102	114	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	14.6	16.4	Voltage applied to the module at DT _{max}
I _{max} (Amps)	3.4	3.4	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	12.2	13.4	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (Ohms)	4.2	4.65	The module resistance is tested under AC
Tolerance	10%		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

1. T100: BiSn (T_{melt}=138°C)
2. T200: CuSn (T_{melt} = 227 °C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

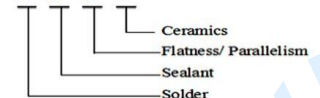
1. Blank ceramics (not metallized)
2. Metallized (Au plating)

Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 10.7± 0.3	0: 0.15/0.15	150±3/Specify
TF	1: 10.7± 0.15	1: 0.1/0.1	150±3/Specify
Eg. TF01: Thickness 10.7±0.3 (mm) and Flatness/ Parallelism 0.1/0.1(mm)			

Naming for the Module

TEC3-127-71-31-03- X-X-X-X



EC3-127-71-31-03-T200-NS-TF01-AIO

T200: CuSn (T_{melt}=227°C)

NS: No sealing

AIO: Alumina white 96%

TF01: Thickness ±0.3(mm) Flatness/ Parallelism 0.1/0.1(mm)

Creative technology with fine manufacturing processes provides you the reliable and quality products

Tel: +86-791-88198288

Fax: +86-791-88198308

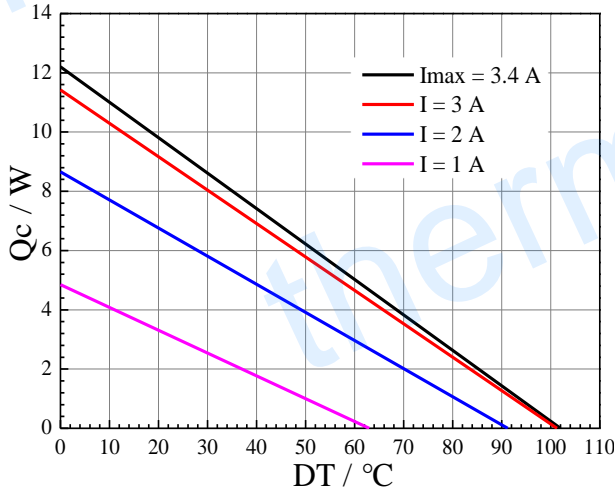
Email: sales@thermonamic.com.cn

Web Site: www.thermonamic.com.cn

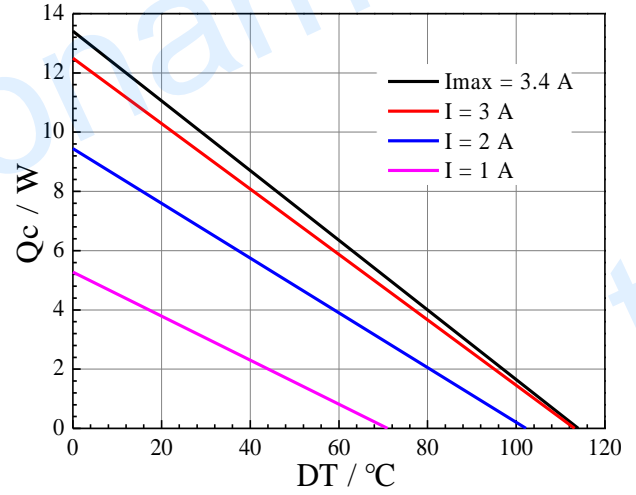
Specification of Thermoelectric Module

TEC3-127-71-31-03

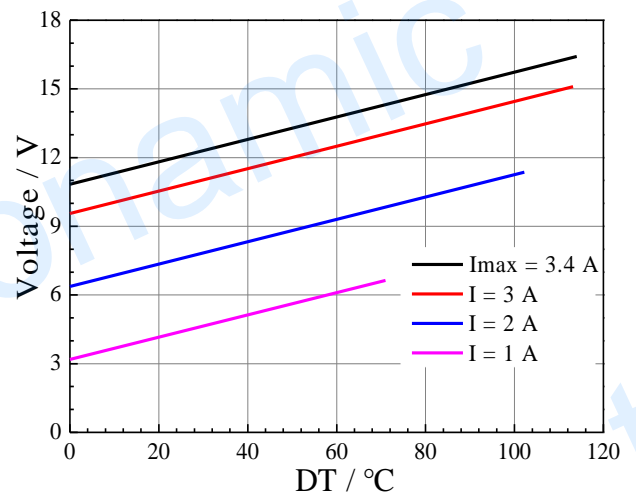
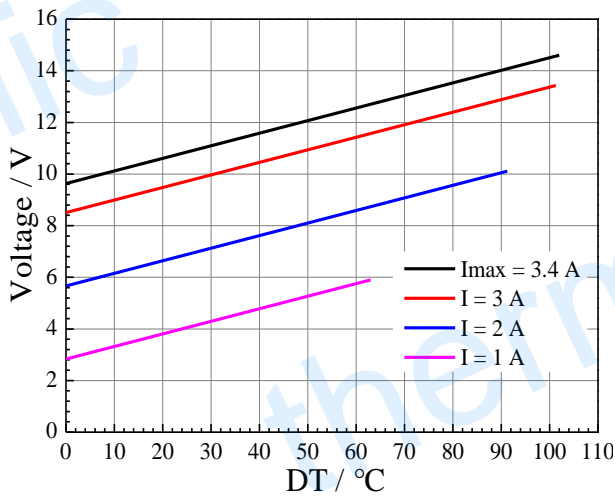
Performance Curves at $T_h=27\text{ }^\circ\text{C}$



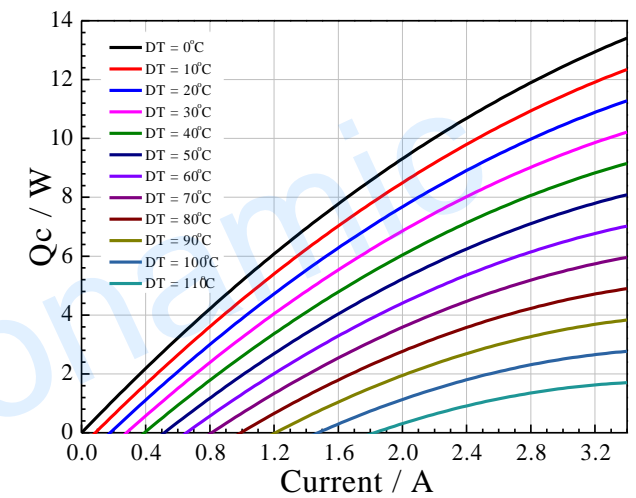
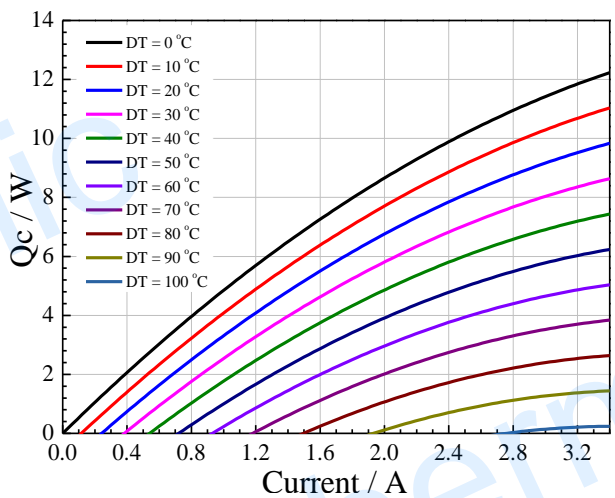
Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$

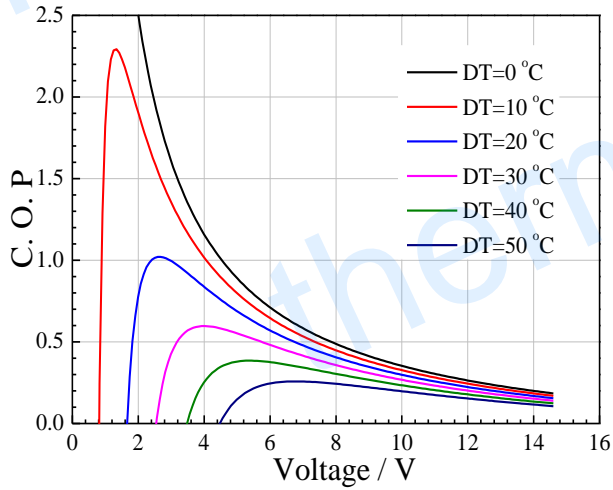


Standard Performance Graph $Q_c = f(I)$

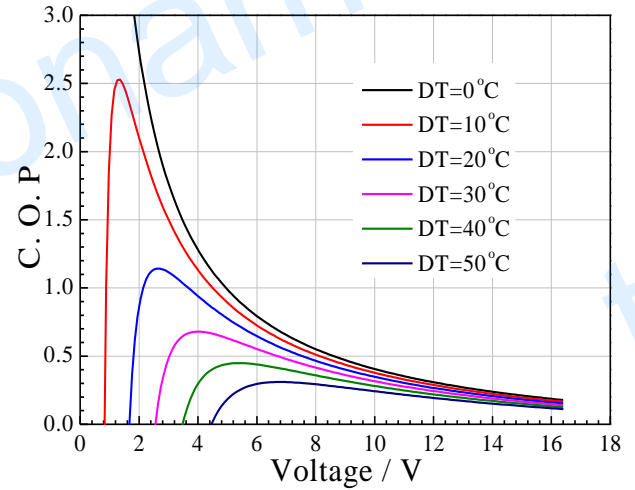
Specification of Thermoelectric Module

TEC3-127-71-31-03

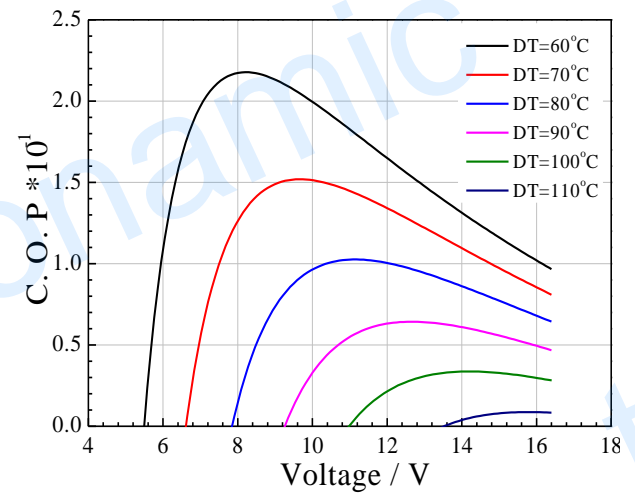
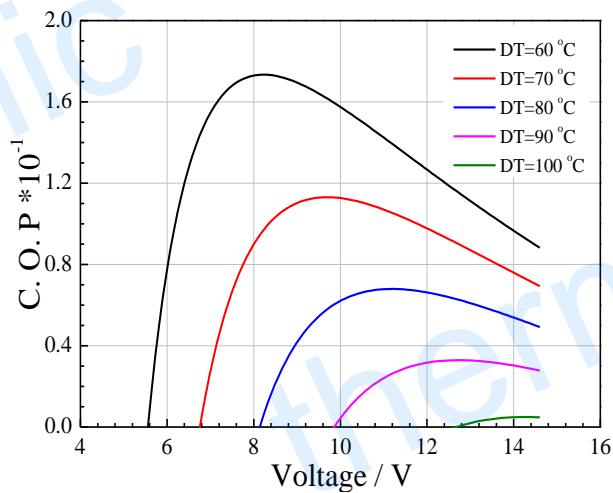
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 50 °C



Standard Performance Graph COP = f(V) of DT ranged from 60 to 100/110 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Cold side of the module stuck on the object being cooled
- Hot side of the module mounted on a heat radiator
- Storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.